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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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#### 3.0mmx1.0 mm RIGHT ANGLE SMD **CHIP LED LAMP**

Part Number: APA3010SGC

Super Bright Green

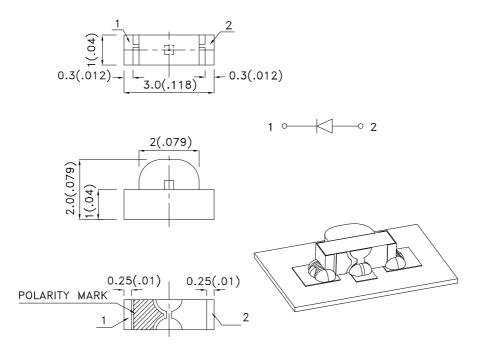
#### **Features**

- 3.0mmx1.0mm RIGHT ANGLE SMT LED, 2.0mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACK LIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS/REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

#### Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. Specifications are subject to change without notice.4.The device has a single mounting surface. The device must be mounted according to the specifications.





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#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		21	Min.	Тур.	201/2
APA3010SGC	Super Bright Green (GaP)	WATER CLEAR	4	15	120°

#### Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Green		10	uA	V <sub>R</sub> =5V

- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

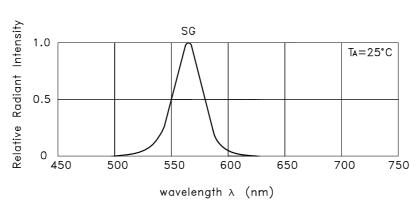
#### Absolute Maximum Ratings at TA=25°C

Alboorato maximum ratingo at 171 20 0				
Parameter	Super Bright Green	Units		
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

#### Note:

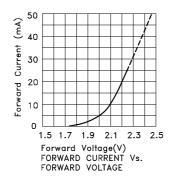
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

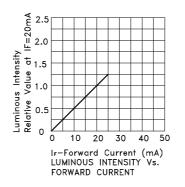
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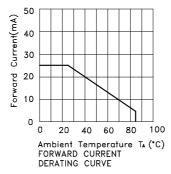


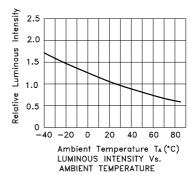
RELATIVE INTENSITY Vs. WAVELENGTH

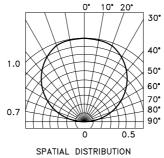
Super Bright Green APA3010SGC









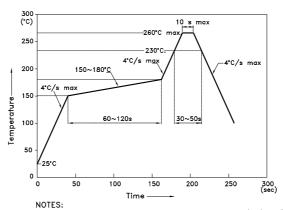


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### APA3010SGC

Reflow Soldering Profile For Lead-free SMT Process.



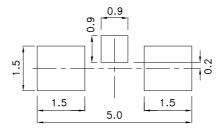
- NOTES:

  1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

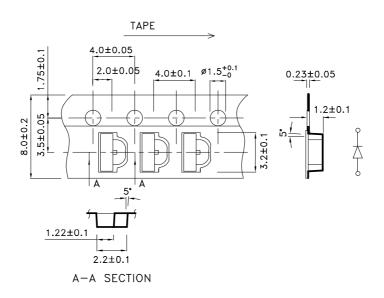
  2. Don't cause stress to the epoxy resin while it is exposed
- to high temperature.

  3.Number of reflow process shall be 2 times or less.

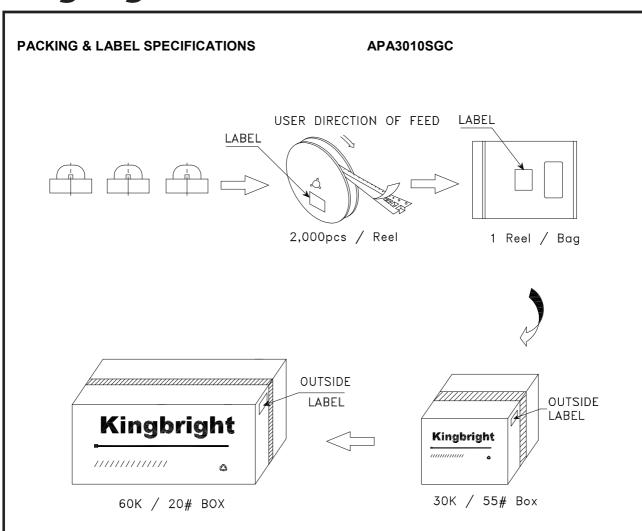
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

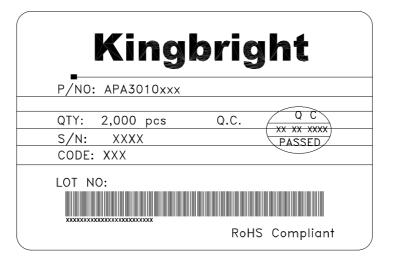


Tape Specifications (Units: mm)



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